

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t3008idc-2.5#trmpbf

(Engineering Calculation)

DFN 2mm X 2mm Exp. Pad

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**TOTAL MASS (g) : 0.009349**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000429	1000000	45885.6679688		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.002935	975000	313926.4375		
		Iron (Fe)	7439-89-6	0.000072	24000	7701.09082031		
		Phosphorus (P)	7723-14-0	0.000001	300	106.959594727		
		Zinc (Zn)	7440-66-6	0.000002	700	213.919189453		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.003010</b>	<b>1000000</b>	<b>321948.40625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000136	1000000	14581.2451172		
		<b>External Plating Total:</b>				<b>0.000136</b>	<b>1000000</b>	<b>14581.2451172</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000072	1000000	7701.09082031		
<b>Internal Plating Total:</b>				<b>0.000072</b>	<b>1000000</b>	<b>7701.09082031</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000351	750000	37542.8164062		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000117	250000	12514.2724609		
<b>Die Attach Total:</b>				<b>0.000468</b>	<b>1000000</b>	<b>50057.0898438</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000677	130000	72411.640625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.004481	860000	479285.9375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000052	10000	5561.89892578		
		<b>Encapsulation Total:</b>				<b>0.005210</b>	<b>1000000</b>	<b>557259.5</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000024	1000000	2567.03051758		
					<b>TOTAL MASS (g) :</b>	<b>0.009349</b>		